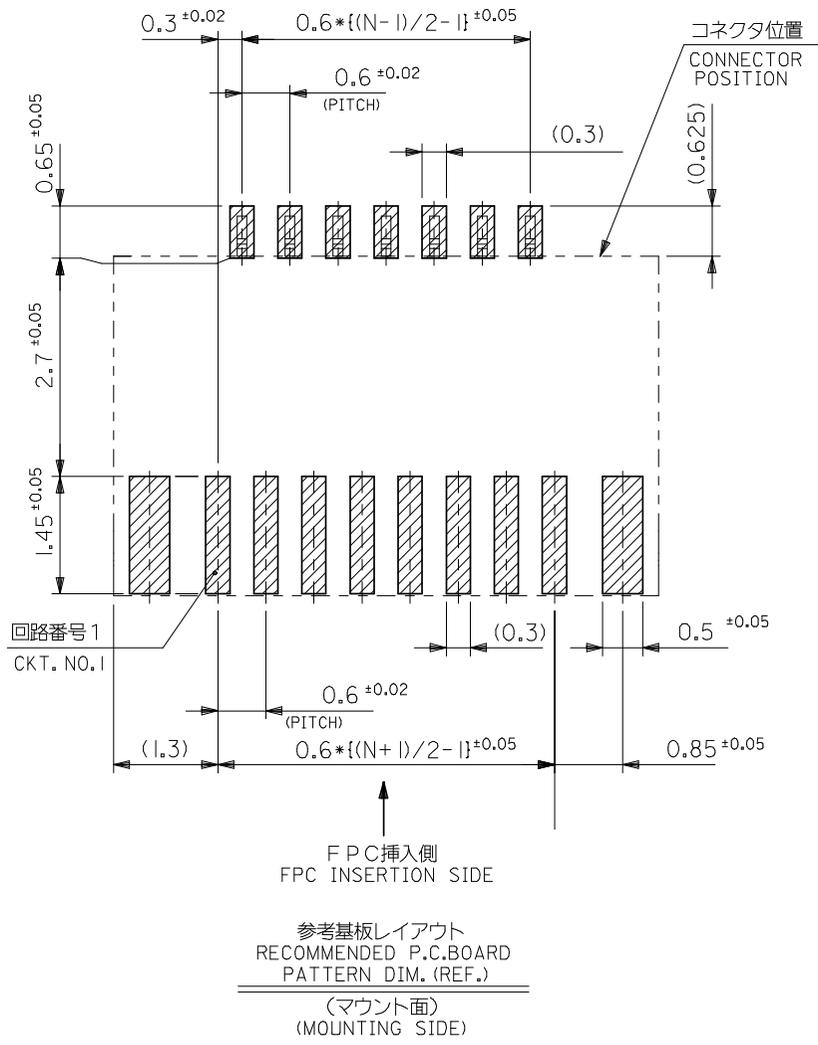


注記 NOTES

1. 使用材料 MATERIAL  
 ハウジング HOUSING : LCP , UL94V-0  
 アクチュエータ ACTUATOR : PA46 , UL94V-0  
 ターミナル : リン青銅 (t=0.12)、ニッケル下地 金メッキ  
 TERMINAL PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING.  
 金具 : リン青銅 (t=0.2)、ニッケル下地 錫メッキ  
 STOPPER PHOSPHOR BRONZE, TIN OVER NICKEL PLATING.
2. ソルダータール半田付け面のズレ量は、基準面 **R** に対し、  
 上方向0MAX.、下方向0.1MAXIMUMとする。  
 又、相互のバラツキ量は0.1MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM **R**  
 UPPER DIRECTION : 0 MAX., LOWER DIRECTION : 0.1 MAXIMUM  
 OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM
3. 一般公差 : ±0.3  
 GENERAL TOLERANCES : ±0.3
4. 本製品は 54809-\*\*67 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 54809-\*\*67.

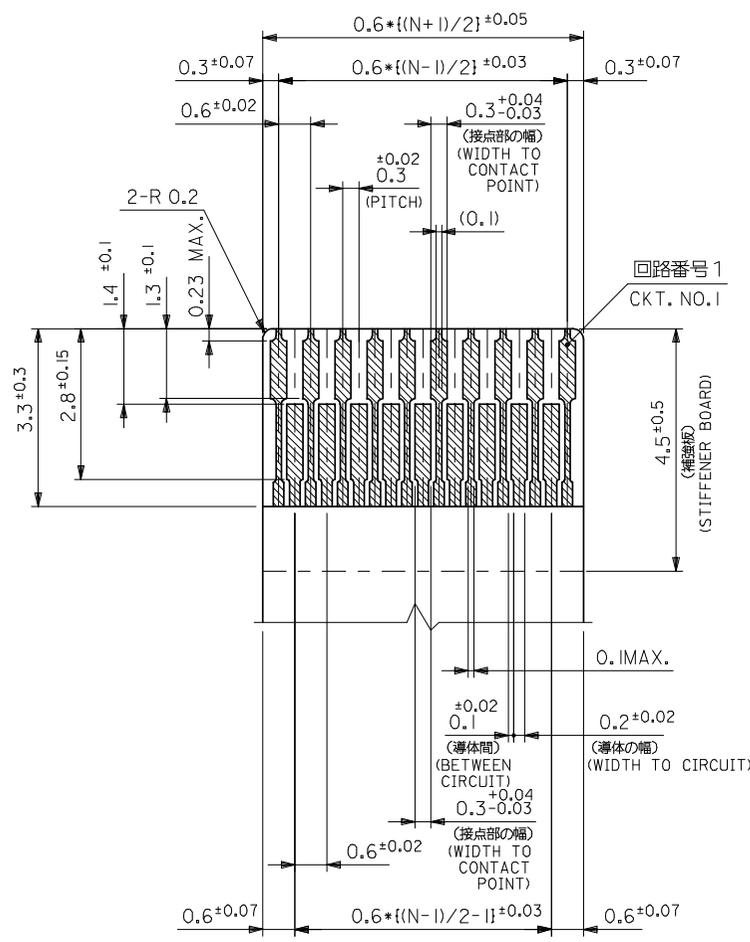
18.6	18.0	17.4	20.6	54809-6175	54809-6169	61
15.6	15.0	14.4	17.6	54809-5175	54809-5169	51
13.8	13.2	12.6	15.8	54809-4575	54809-4569	45
12.0	11.4	10.8	14.0	54809-3975	54809-3969	39
11.4	10.8	10.2	13.4	54809-3775	54809-3769	37
10.8	10.2	9.6	12.8	54809-3575	54809-3569	35
10.2	9.6	9.0	12.2	54809-3375	54809-3369	33
9.6	9.0	8.4	11.6	54809-3175	54809-3169	31
8.4	7.8	7.2	10.4	54809-2775	54809-2769	27
7.8	7.2	6.6	9.8	54809-2575	54809-2569	25
6.6	6.0	5.4	8.6	54809-2175	54809-2169	21
6.0	5.4	4.8	8.0	54809-1975	54809-1969	19
4.8	4.2	3.6	6.8	54809-1575	54809-1569	15
3.6	3.0	2.4	5.6	54809-1175	54809-1169	11
D	C	B	A	EMBOSSED TAPE		MATERIAL NO.
				ORDER No. オーダー番号		CIRCUITS

REVISED EC NO: J2008-4034 DRW: MNABEI CHKD: THARYAMA APPR: NUKITA 2008/05/28 2008/05/28 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TUENO	DATE '04/02/10	TITLE 0.3 FPC CONN E/O HSG ASSY GOLD PLT H=1.3 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE '04/02/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-54809-038	SHEET NO. 1 OF 3
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

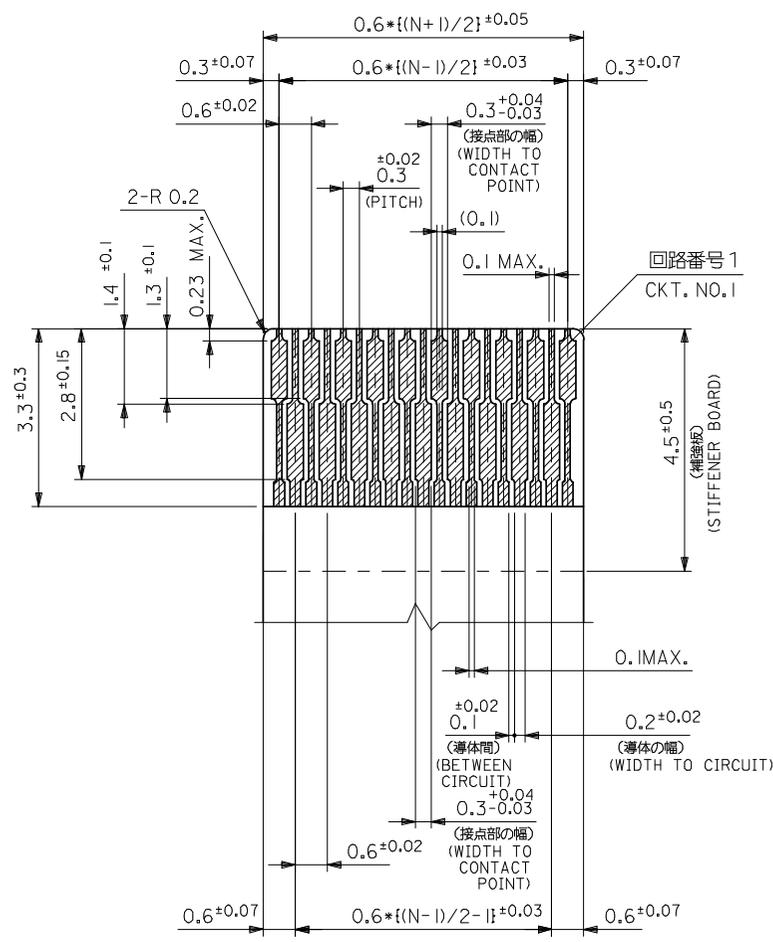


REVISED EC NO: J2008-4034 DRWN: NABEI CHKD: THARYAMA APPR: NUKITA 2008/05/28 2008/05/28 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		54809-***69		MODEL NO.	
	10 UNDER ± 0.2		DRAWN BY DATE TUENO '04/02/10		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER ± 0.25		CHECKED BY DATE MSASAO '04/02/10		TITLE 0.3 FPC CONN E/O HSG ASSY GOLD PLT H=1.3 -LEAD FREE-			
	30 OVER ± 0.3		APPROVED BY DATE MSASAO '04/02/10		MOLEX INCORPORATED			
	ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54809-038		2 OF 3	

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



適合FPC推奨寸法 1  
 APPLICABLE FPC  
 RECOMMENDED DIM. NO.1  
 (仕上がり厚さ:  $0.2 \pm 0.03$ )  
 (THICKNESS :  $0.2 \pm 0.03$ )



適合FPC推奨寸法 2  
 APPLICABLE FPC  
 RECOMMENDED DIM. NO.2  
 (仕上がり厚さ:  $0.2 \pm 0.03$ )  
 (THICKNESS :  $0.2 \pm 0.03$ )

FPCについて:  
 打抜き方向は導体側から補強板側を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC :  
 RECOMMENDED PUNCHER DIRECTION :  
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2008-4034 DRWN: MWABEI 2008/05/28 CHKD: THARUYAMA 2008/05/28 APPR: NUKITA 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		54809-***69		MODEL NO.	
	10 UNDER ±0.2		DRAWN BY DATE YSAKIYAM '04/06/15		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION
	10 OVER 30 UNDER ±0.25		CHECKED BY DATE MHAYASHI '04/06/15		TITLE 0.3 FPC CONN E/O HSG ASSY GOLD PLT H=1.3 -LEAD FREE-			
	30 OVER ±0.3		APPROVED BY DATE MSASAO '04/06/15		MOLEX INCORPORATED			
	ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54809-038		SHEET NO. 3 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				